

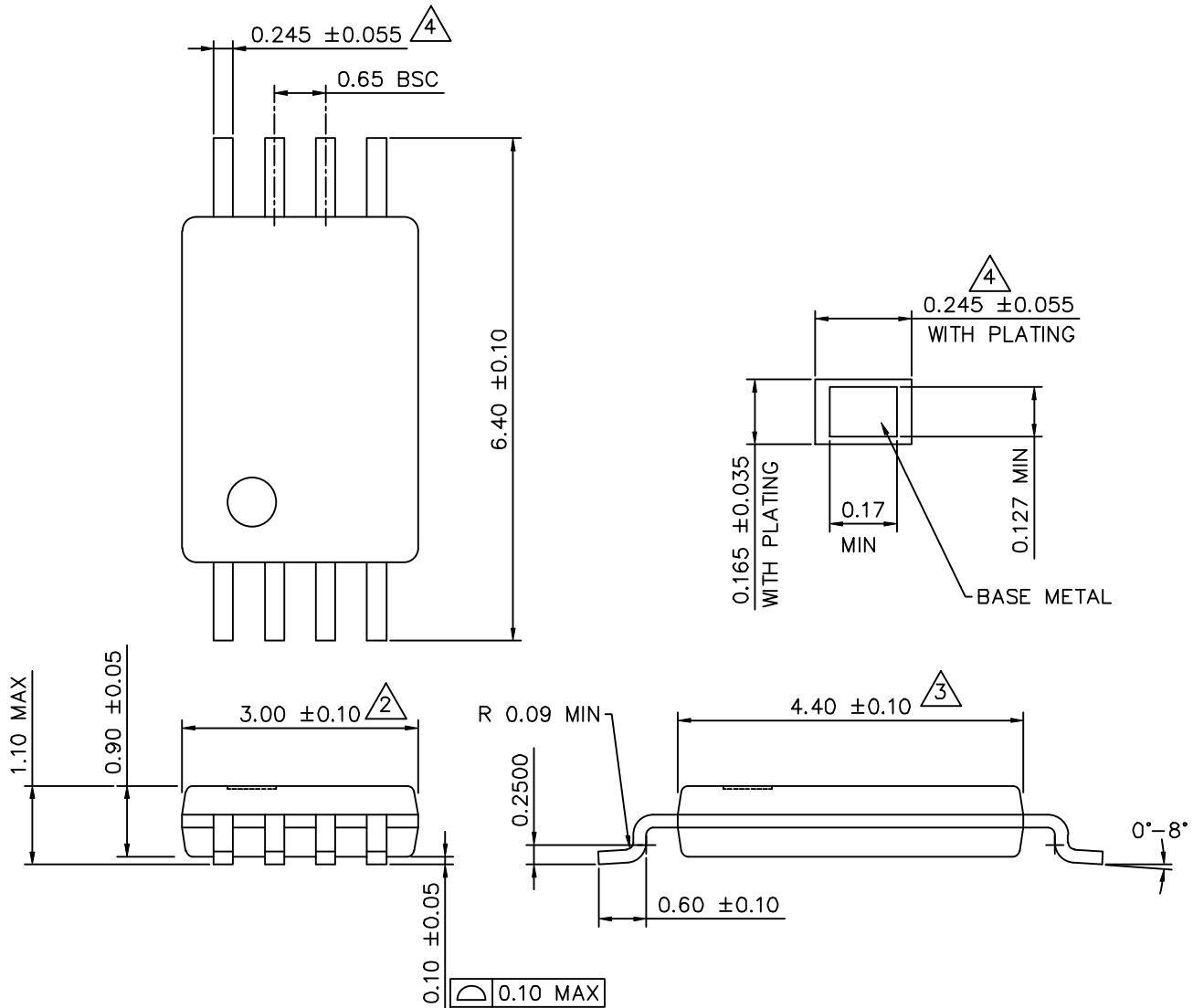
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

ON Semiconductor®



TSSOP8 4.4x3.0
CASE 948BJ
ISSUE A

DATE 30 SEP 2015



NOTES:

1. THIS PART IS COMPLIANT WITH JEDEC SPECIFICATION MO-153, VARIATION AA.
2. DOES NOT INCLUDE MOLD FLASH, PROTRUSION OR GATE BURRS. PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED 0.15 mm PER SIDE.
3. DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 mm PER SIDE.
4. DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 mm.
5. LEAD SPAN/STAND OFF HEIGHT/COPLANARITY ARE CONSIDERED AS SPECIAL CHARACTERS.

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STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	TSSOP8 4.4X3.0	PAGE 1 OF 2

